

2. (Amended) The interconnect substrate as defined in claim 1,
wherein each of the end parts as the positioning references includes two edges which
are perpendicular to each other.

C1
C2
3. (Amended) The interconnect substrate as defined in claim 1,
wherein the first portion comprises a rectangular body section and a projected
section which extends from at least one edge of the body section and includes one of the end parts.

4. (Amended) The interconnect substrate as defined in claim 3,
wherein the projected section is a region determined by:
an edge which is a boundary between the projected section and the body section;
a first edge which is perpendicular to the edge as a boundary; and
a second top edge which is parallel to the edge as a boundary,
wherein one of the end parts as the positioning references includes the first and
second edges.

C2
7. (Amended) The interconnect substrate as defined in claim 6,
wherein at least one of the end parts is formed from an area in the body section other
than an area from which the projected section extends.

C3
10. (Twice Amended) The interconnect substrate as defined in claim 1, wherein a
plurality of holes are formed in the end parts.

C4
13. (Twice Amended) A semiconductor device comprising:
at least one semiconductor chip; and
a substrate which has a first portion and a second portion to be superposed on the
first portion, and on which the semiconductor chip is mounted,
wherein the first portion includes end parts as positioning references; and
wherein the second portion has a shape so as to be superposed inside the first portion
and avoid being superposed over the end parts of the first portion, the second portion positioned
between the end parts.